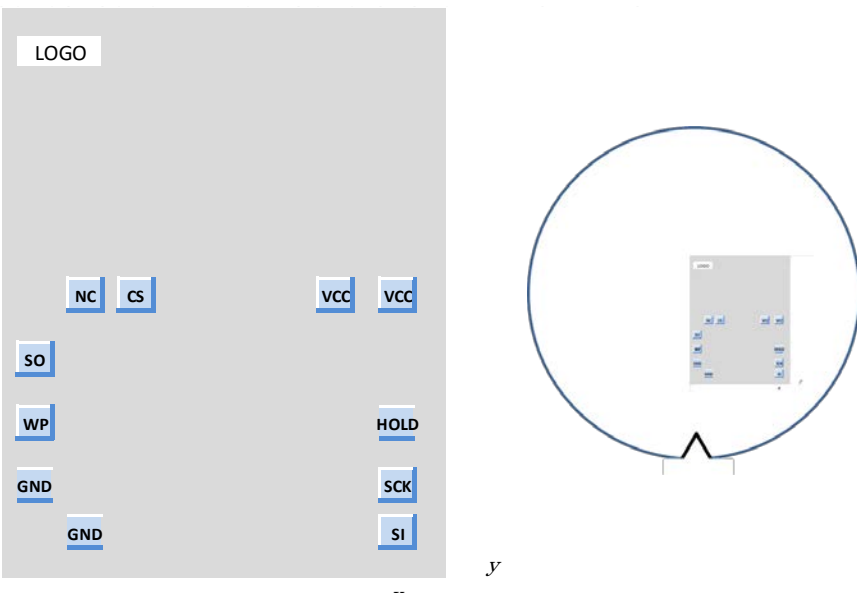


WAFER PRODUCT DATASHEET (ADDENDUM)

Product	AT25SL321-DWF																																														
Description	32Mbit, Standard Serial Flash, 1.7V – 2.0V VCC																																														
Die Map	 <p style="text-align: center;">Image reflects relative pad positioning only; not representative of actual die</p>																																														
Die Size & Pad Coordinates	<table border="1" style="width: 100%; border-collapse: collapse;"> <thead> <tr> <th></th> <th style="text-align: center;">X (μm)</th> <th style="text-align: center;">Y (μm)</th> </tr> </thead> <tbody> <tr> <td>Die Size⁽¹⁾</td> <td style="text-align: center;">1596</td> <td style="text-align: center;">2329</td> </tr> <tr> <td>Scribe Line Width</td> <td style="text-align: center;">60</td> <td style="text-align: center;">60</td> </tr> <tr> <td>Pad Opening</td> <td style="text-align: center;">65</td> <td style="text-align: center;">65</td> </tr> <tr> <td>CS</td> <td style="text-align: center;">-580</td> <td style="text-align: center;">-658.5</td> </tr> <tr> <td>SO_IO1</td> <td style="text-align: center;">-690</td> <td style="text-align: center;">-786.5</td> </tr> <tr> <td>WP_IO2</td> <td style="text-align: center;">-690</td> <td style="text-align: center;">-868.5</td> </tr> <tr> <td>VCC</td> <td style="text-align: center;">562</td> <td style="text-align: center;">-744.5</td> </tr> <tr> <td>VCC</td> <td style="text-align: center;">690</td> <td style="text-align: center;">-744.5</td> </tr> <tr> <td>HOLD_RESET_IO3</td> <td style="text-align: center;">690</td> <td style="text-align: center;">-908.5</td> </tr> <tr> <td>SCK</td> <td style="text-align: center;">690</td> <td style="text-align: center;">-996.5</td> </tr> <tr> <td>SI_IO0</td> <td style="text-align: center;">690</td> <td style="text-align: center;">-1080.5</td> </tr> <tr> <td>GND</td> <td style="text-align: center;">-690</td> <td style="text-align: center;">-950.5</td> </tr> <tr> <td>GND</td> <td style="text-align: center;">-662</td> <td style="text-align: center;">-1080.5</td> </tr> <tr> <td>NC</td> <td style="text-align: center;">-676</td> <td style="text-align: center;">-658.5</td> </tr> </tbody> </table> <p style="text-align: right; font-size: small;">⁽¹⁾ includes scribe line</p>			X (μm)	Y (μm)	Die Size ⁽¹⁾	1596	2329	Scribe Line Width	60	60	Pad Opening	65	65	CS	-580	-658.5	SO_IO1	-690	-786.5	WP_IO2	-690	-868.5	VCC	562	-744.5	VCC	690	-744.5	HOLD_RESET_IO3	690	-908.5	SCK	690	-996.5	SI_IO0	690	-1080.5	GND	-690	-950.5	GND	-662	-1080.5	NC	-676	-658.5
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Technical Details	
Adesto Product Family	Standard Flash
Density	32 Mbit
Operating Vcc	1.7V – 2.0V
ESD	JESD22-A114
Delivery Option	Wafer- unsawn
Wafer Size (mm)	300 mm
Process Geometry (nm)	90 nm
Die ID	25M32
Wafer Map	Electronic- text file
Wafer Thickness (µm) Maximum	800
Back Grind Options	None / Contact Adesto
Back Plane Connection	Floating / Not Required
Backside preparation / metallization	None
Bond wire qualified	AU <input type="checkbox"/> CU <input type="checkbox"/> AG <input checked="" type="checkbox"/>
Passivation Material	PETEOS + SiON
Passivation Thickness (Å)	11000
Bond Pad Material	TaN/AlCu
Bond Pad Thickness (Å)	9500
Active Circuits underneath the bond pad	Yes

¹ Average value; subject to change without notice.

Part Number Ordering Code	Operating Temperature Range	Functional Specification
AT25SL321-DWF	-40°C to 85°C	http://www.adestotech.com/wp-content/uploads/AT25SL321_112.pdf

Revision Level – Release Date	History
A – August 2017	Initial release.

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